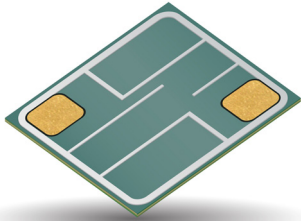


Thin Film WBR (Wire Bond Resistor)

Top Contact



GENERAL DESCRIPTION

Top Contact Precision wire bondable resistors are ultra-stable with high reliability. Resistors are laser trimmed to tight tolerance. Customizable value and unique marking of that value. This device is built in 0202 chip outline and is ideal for but not limited to hybrid circuit applications.

These are designed specifically for applications that require thermo-compression, epoxy or ultra-sonic attachment.

BENEFITS

- Top Contact/ Bottom Isolated
- Ultra High Stability
- High Reliability
- Extremely Tight Tolerance
- Unique Value Marking
- 250 mW Power Rating
- Small package size

APPLICATIONS

- Medical Implantable
- Military / Defense
- Hybrid Designs
- Multi-Chip Module (MCM)
- Test & Measurement Instrumentation
- High-Rel Microelectronics
- RF / Microwave communications

HOW TO ORDER

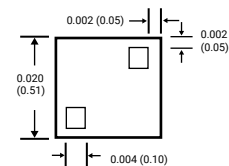
WBR	0202	S	C	1R051	F	G	W
Series Code	Case Size	Material	TCR (ppm/°C)	Resistance	Tolerance	Termination Code	Packaging
WBR = Wire Bond Resistor	0202 = 0202 OSOS = Special Request Please supply Design or contact factory	S = Silicon G = Glass C = Custom	A = ±25 B = ±50 C = ±100 (standard) D = ±150 S = Special Request supply design or contact factory	Example Values 1R500=1.5 ohm 1R051=10.5ohm 1R052=105ohm 1R053=1,050ohm 2R553=2,550ohm 1R054=10,500ohm 1R007=10Megohm	D = ±0.5% F = 1% G = 2% J = 5% S = Special Request supply design or contact factory	G = Bondable Gold A = Aluminum	W = Waffle Pack

MECHANICAL DIMENSIONS

Size	Length (L)	Width (W)	Minimum Bond Area
0202	0.020 ± 0.003 (0.51 ± 0.076)	0.020 ± 0.003 (0.51 ± 0.076)	0.0038 ± 0.0038 (0.09 x 0.09)

Inches (mm)

Other sizes available upon request



GENERAL CHARACTERISTICS

Resistance Range	1.0 Ohm - 10.0 Mohm
Resistance Tolerance	± 1%, ± 2% ± 0.1%, ± 0.5%
Termination Type	Gold, Aluminum
Backing	Bare (Lapped) Substrate
Operating Temperature	-55°C ± 125°C
Insulation Resistance	10 ⁶ MOhm

Custom values up to 10meg Ohm available upon request

ENVIRONMENTAL TESTS

Test	Limits	Specification
Life Test/ Stability	±0.25% Max Δ R/R	MIL-STD-202 MTD 108, 1000hrs, 125°C, 50mW
Thermal Shock	±0.25% Max Δ R/R	MIL-STD-202 MTD 107
High Temperature Exposure	±0.25% Max Δ R/R	100 Hrs @ 150°C
Moisture Resistance	±0.25% Max Δ R/R	MIL-STD-202 MTD 106
Wire Bond Test	4 Gram Min (1.25 Mil Wire)	MIL -PRF-55342
Short Time Overload	±0.25% Max Δ R/R	MIL -PRF-55342